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(19) **United States**(12) **Patent Application Publication** (10) **Pub. No.: US 2023/0232591 A1****Bekaert et al.**(43) **Pub. Date: Jul. 20, 2023**(54) **ELECTRONIC PACKAGE COMPRISING A COMPONENT TO BE COOLED AND ASSOCIATED MOUNTING METHOD****Publication Classification**(51) **Int. Cl.**
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CPC **H05K 7/20863** (2013.01); **H05K 7/20163** (2013.01); **H05K 7/20172** (2013.01)(71) Applicant: **Continental Automotive Technologies GmbH**, Hannover (DE)(72) Inventors: **Jean-Philippe Bekaert**, Toulouse (FR);
Gilles Le Roy, Toulouse (FR)(57) **ABSTRACT**(21) Appl. No.: **18/012,350**(22) PCT Filed: **Jul. 7, 2021**(86) PCT No.: **PCT/EP2021/068751**§ 371 (c)(1),
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A set of electronic package elements intended to be mounted on an electronic board having a component to be cooled including: a chassis, a heatsink fixed by a retaining piece inside the chassis, a cover configured to be fixed on the chassis so as to retain the electronic board in the package. The heatsink is configured to be fixed on the electronic board while maintaining a predetermined distance between a lower face of the heatsink and the component. The cover is configured to be able to be fixed by a fixing point to the heatsink. The retaining piece is connected to the heatsink so as to allow the heatsink a translational movement relative to the chassis in three orthogonal directions.

(30) **Foreign Application Priority Data**

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